Special Issue

Seismic Structural Health Monitoring

Message from the Guest Editors

Recently, various nanotechnologies have enabled the development of an increasing number of smart sensors. These smart sensors and smart devices are often combined with various structures to form so-called smart structures, which can sense environmental or structural changes during an earthquake. With developments in microprocessor technology, wireless communications, and sensor networks, smart sensors and smart structures are finding a wider range of applications in structural health monitoring, damage detection, and localization of damaged places in earthquake engineering and other disciplines. These advances are essential towards building an infrastructure that is able to automatically handle the threats that are posed by earthquake phenomena to the integrity of structures and increase the safety of occupants. This Special Issue aims to archive some of the latest developments in seismic damage detection and structural health monitoring in the hope of inspiring potential readers and researchers in the field and of bringing us closer to a world in which intelligent structures are commonplace.

Guest Editors

Prof. Dr. Wen-I Liao
National Taipei University of Technology, Taipei, Taiwan

Prof. Dr. Chien-Kuo Chiu
National Taiwan University of Science and Technology, Taipei, Taiwan

Deadline for manuscript submissions

closed (30 September 2020)

Applied Sciences

About the Journal

Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

Editor-in-Chief

Prof. Dr. Giulio Nicola Cerullo
Dipartimento di Fisica, Politecnico di Milano, Piazza L. da Vinci 32, 20133 Milano, Italy

Author Benefits

Open Access:
free for readers, with article processing charges (APC) paid by authors or their institutions.

High Visibility:
indexed within Scopus, SCIE (Web of Science), Ei Compendex, Inspec, CAPlus / SciFinder, and other databases.

Journal Rank:
JCR - Q2 (Engineering, Multidisciplinary) / CiteScore - Q1 (General Engineering)